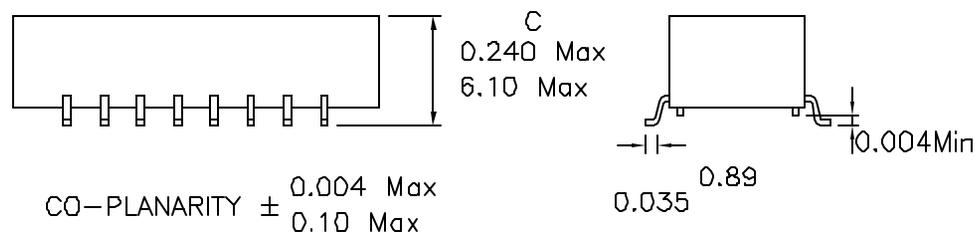
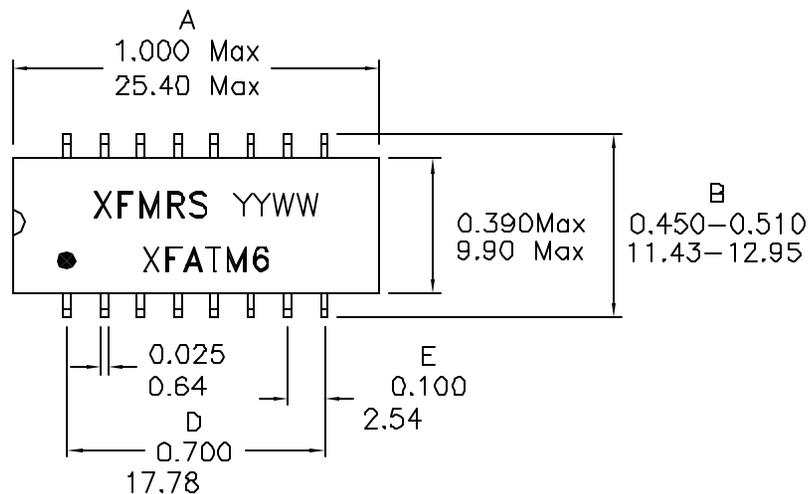
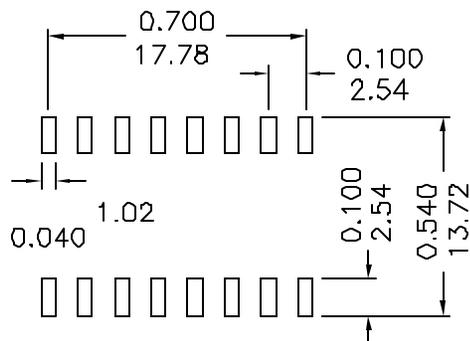


## 1. Mechanical Dimensions:



CO-PLANARITY  $\pm$  0.004 Max  
0.10 Max

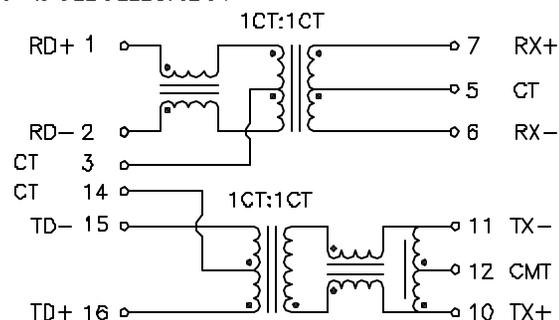


SUGGESTED FOOTPRINT

### Notes:

- Solderability: Leads shall meet MIL-STD-202, Method 208D for solderability.
- Flammability: UL94V-0
- ASTM oxygen index: > 28%
- Insulation System: Class F 155°C, UL file E151556
- Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
- Storage Temperature Range: -55°C to +125°C
- Aqueous wash compatible
- SMD Lead Coplanarity:  $\pm 0.004^*$  (0.102mm)
- Moisture Sensitivity: Level 3
- Electrical and mechanical specifications 100% tested
- RoHS Compliant Component

## 2. Schematic:



## 3. Electrical Specifications: @25°C

Isolation Voltage: 1500 Vrms

CHIP SIDE OCL: 350uH Min @100KHz 0.1V 8mA

Rise Time (10-90%): 4.0ns Typ

Insertion Loss (100KHz-100MHz): -1.0dB Max

Return Loss: 1-30MHz 40MHz 50MHz 60MHz-80MHz  
-20dB -20dB -18dB -14dB (Min)

CMRR: 30MHz 60MHz 100MHz  
-42dB -36dB -33dB (Min)

CROSSTALK: 30MHz 60MHz 100MHz  
-50dB -40dB -40dB (Min)

DOC. REV. F/15

**PROPRIETARY**

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**XFMRs Inc.**  
www.XFMRs.com

Title:  
HIGH SPEED LAN MAGNETICS

UNLESS OTHERWISE SPECIFIED  
TOLERANCES:  
.xxx  $\pm 0.010$  Inch  
Dimensions in Inch/mm

P/N: XFATM6	REV. F
DWN. 罗振江	Aug-15-05
CHK. 廖玉坤	Aug-15-05
APP. BW	Aug-15-05

SCALE 2:1 SHT 1 OF 1